

## Application Data Sheet

### **Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
Suggested Group Art Unit:: N/A  
CD-ROM or CD-R?:: None  
Sequence submission?:: None  
Computer Readable Form (CRF)?:: No  
Title:: METHOD FOR PRODUCING A DEEP  
TRENCH CAPACITOR IN A  
SEMICONDUCTOR SUBSTRATE  
Attorney Docket Number:: 543822005300  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Total Drawing Sheets:: Thirteen (13)  
Small Entity?:: No  
Petition included?:: No  
Secrecy Order in Parent Appl.?:: No

### **Applicant Information**

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Taiwan  
Status:: Full Capacity  
Given Name:: Steve  
Family Name:: WANG  
City of Residence:: Dresden  
Country of Residence:: Germany  
Street of mailing address:: Sagarder Weg 2  
City of mailing address:: Dresen  
Country of mailing address:: Germany  
Postal or Zip Code of mailing address:: D-01109

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Taiwan  
Status:: Full Capacity  
Given Name:: Kae-Horng  
Family Name:: WANG  
City of Residence:: Dresden  
Country of Residence:: Germany  
Street of mailing address:: Tieckstrasse 10  
City of mailing address:: Dresden  
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Postal or Zip Code of mailing address:: D01099

#### Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::

#### Correspondence Information

Correspondence Customer Number:: 25227

#### Representative Information

Representative Customer Number:: 25227

#### Assignee Information

Assignee name:: Infineon Technologies AG  
Street of mailing address:: St.-Martin-Str. 53  
City of mailing address:: München  
Country of mailing address:: Germany  
Postal or Zip Code of mailing address:: 81669